W3NL SERIES

1. PART NO. EXPRESSION:

<u>W 3 N L 6 7 0 - R D - 1 0</u>

(a) Series code

(e) R : Tape & Reel

(a)(b) (c) (d) (e)(f) (g)

(b) Dimension code

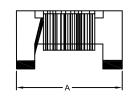
(f) Current code : D = 400mA

(c) Material code

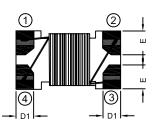
(g) 10: RoHS Compliant

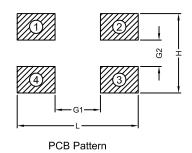
(d) Impedance code : $670 = 67\Omega$

2. CONFIGURATION & DIMENSIONS:





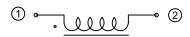


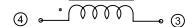


Unit:m/m

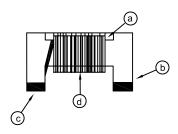
А	В	С	D1	E	G1	G2	Н	L
2.0±0.2	1.2±0.2	1.0±0.1	0.47±0.05	0.48±0.05	1.10 Ref.	0.45 Ref.	1.25 Ref.	2.60 Ref.

3. SCHEMATIC:





4. MATERIALS :



- (a) Upper Plate
- (b) Core
- (c) Termination
- (d) Wire

RoHS Compliant

NOTE: Specifications subject to change without notice. Please check our website for latest information.



W3NL SERIES

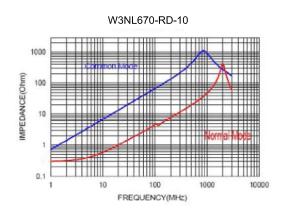
5. GENERAL SPECIFICATION:

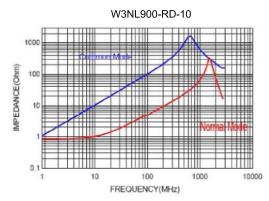
a) Operating temp.: -40°C to +105°Cb) Storage temp.: -40°C to +105°C

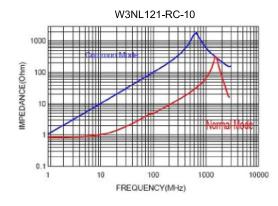
6. ELECTRICAL CHARACTERISTICS:

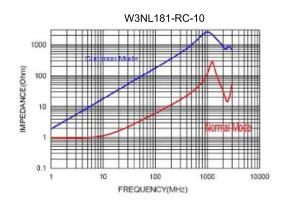
Part No.	Common mode Impedance (Ω)	Test Frequency (MHz)	DCR (Ω) Max.	Rated Current (mA) Max.	Rated Volt. (Vdc) Max.	Withstand Volt. (Vdc) Max.	IR (Ω) Min.
W3NL670-RD-10	67±25%	100	0.35	400	50	125	10M
W3NL900-RD-10	90±25%	100	0.35	400	50	125	10M
W3NL121-RC-10	120±25%	100	0.45	300	50	125	10M
W3NL181-RC-10	180±25%	100	0.50	300	50	125	10M

7. CHARACTERISTICS CURVES:











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8. RELIABILITY & TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION			
Electrical Characteristics Tes	st				
Z (common mode)		Agilent-4291A+ Agilent -16197A			
DCR	Refer to standard electrical characteristics list	Agilent-4338B			
I.R.		Agilent4339			
Temperature Rise Test	Rated Current < 1A	Applied the allowed DC current.			
	Rated Current ≧ 1A ∆T 40°CMax	2. Temperature measured by digital surface thermometer			
Mechanical Performance Te	st				
Solderability Test	More than 95% of termincal electrode should be covered with solder.	Preheat: 150°C,60sec. Solder: Sn99.5%-Cu0. 5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5% Dip time: 4±1sec Depth: completely cover the termination			
Solder Heat Resistance Terminal Strength	Appearance: No damage. Impedance: within±15% of initial value RDC: within ±15% of initial value and shall not	Temperature (°C) (s) Temperature ramp/immersion and emersion rate (solder temp) 10 ±1 25mm/s±6 mm/s 1 Depth: completely cover the termination.			
	exceed the specification value	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile With the component mounted on a PCB with the devic to be tested, apply a force (>0805:1kg, <=0805:0.5kg) the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be appl gradually as not to apply a shock to the component be tested. DUT DUT			
		substrate press tool shear force			



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8. RELIABILITY & TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION					
Reliabilty Test							
Life Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 85±2°C Applied Current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs.					
Thermal Shock	Appearance: No damage.	1	ning: Run through IR refl C J-STD-020D Classifica				
	Impedance: within±15% of initial value	Step	Temperature (°C)	Times (min.)			
	RDC: within ±15% of initial value and shall not exceed the specification value	1	-40±2	30±5			
		2	25±2	≦0.5			
		3	105±2	30±5			
		Number of cycles: 500 Measured at room fempraturc after placing for 24±2 hrs					
Humidity Resistance Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 85±2°C Humidity: 85±2% R.H Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs					
Vibration Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude: 1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).					



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W3NL SERIES

9. SOLDERING AND MOUNTING:

9-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-1.1 Solder Re-flow:

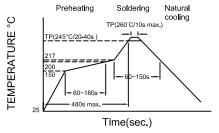
Recommended temperature profiles for re-flow soldering in Figure 1.

9-1.2 Soldering Iron (Figure 2):

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

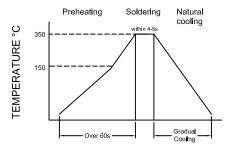
Note:

- a) Preheat circuit and products to 150°C
- b) 355°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max.

Fig.1



Iron Soldering times: 1 times max.

Fig.2



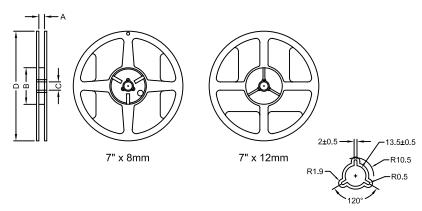
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W3NL SERIES

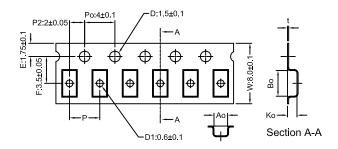
10. PACKAGING INFORMATION:

10-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 8mm	9.0±0.5	60.0±2.0	13.5±0.5	178.0±2.0

10-2 Tape Dimension / 8mm



Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
W3N	2.25±0.10	1.42±0.10	1.04±0.10	4.0±0.1	0.22±0.05

10-3 Packaing Quantity

Chip Size	W3N	
Chip / Reel	4000	
Inner Box	20000	
Middle Box	100000	
Carton	200000	



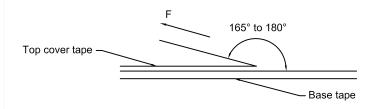
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W3NL SERIES

10. PACKAGING INFORMATION:

10-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(°C)	(%)	(hPa)	(mm/min)
5~35	45~85	860~1060	300

Application Notice

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Temperature and humidity conditions: Less than 40°C and 60% RH.
- b) Recommended products should be used within 12 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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